

Semiconductor die products —

Part 4: Questionnaire for die users and suppliers

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National foreword

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A list of organizations represented on this committee can be obtained on request to its secretary.

This publication does not purport to include all the necessary provisions of a contract. Users are responsible for its correct application.

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TECHNICAL REPORT

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INTRODUCTION

This technical report is based on the work carried out in the ESPRIT 4th Framework Project GOODDIE which resulted in the publication of the ES 59008 series of European specifications. Organizations that helped prepare this document included the ESPRIT ENCAST and ENCASIT projects, the Die Products Consortium, JEITA, JEDEC and ZVEI.

SEMICONDUCTOR DIE PRODUCTS –

Part 4: Questionnaire for die users and suppliers

1 Scope

This part of IEC 62258 has been developed to facilitate the production, supply and use of semiconductor die products, including

- wafers;
- singulated bare die;
- die and wafers with attached connection structures;
- minimally or partially encapsulated die and wafers.

This technical report contains a questionnaire, based on the requirements of other parts of IEC 62258, which may be used in negotiations and contracts between suppliers and purchasers of die devices. It is intended to assist all those involved in the supply chain for die devices to comply with the requirements of the IEC 62258-1 and IEC 62258-2 standards.

It should be recognized that the tables contained in this technical report form a checklist of information that can potentially be supplied and that it may not be relevant or possible to complete all fields. Different markets may require different subsets of the information requested herein.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60050, *International Electrotechnical Vocabulary*

IEC 62258-1:2005, *Semiconductor die products – Part 1: Requirements for procurement and use*

IEC 62258-2:2005, *Semiconductor die products – Part 2: Exchange data formats*

3 Terms and definitions

For the purposes of this document, the terms and definitions given in IEC 60050 and IEC 62258-2 apply.

4 General

To comply with IEC 62258-1, that standard requires that suppliers of die devices furnish information which is necessary and sufficient for users of the devices at all stages of design, procurement, manufacture and test of the products containing them. The questionnaire in Annex A provides a *pro forma* that can form a standard basis for supplying such information and is intended as an aid to compliance with the standard.

Where references are made in this technical report to clauses in IEC 62258-1 and IEC 62258-2, these references are only to the clauses in the 2005 editions. The tables in the